MA3Z7930G

Silicon epitaxial planar type

For super high speed switching
For small current rectification

■ Features

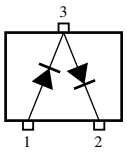
- Two MA3Z792 (MA792) is contained in one package (series connection)
- $I_{F(AV)}$ = 100 mA rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- Low forward voltage V_F and good rectification efficiency

■ Package

- Code
  SMini3-F2
- Pin Name
  1: Anode 1
  2: Cathode 2
  3: Cathode 1
  Anode 2

■ Marking Symbol: M4A

■ Internal Connection



■ Absolute Maximum Ratings T_a = 25°C

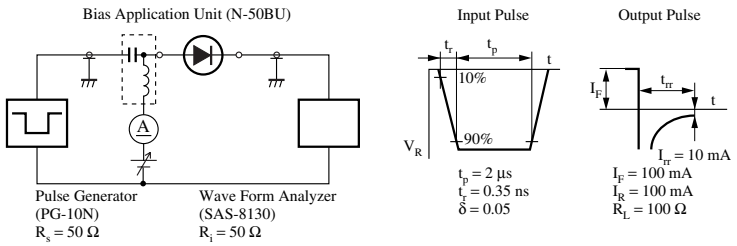
Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Repetitive peak reverse voltage		V_{RRM}	30	V
Forward current	Single	I_F	100	mA
	Series		70	
Peak forward current	Single	I_{FM}	300	mA
	Series		200	
Non-repetitive peak forward surge current *		I_{FSM}	1	A
Junction temperature		T_j	125	°C
Storage temperature		T_{stg}	−55 to +125	°C

Note) ∗: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

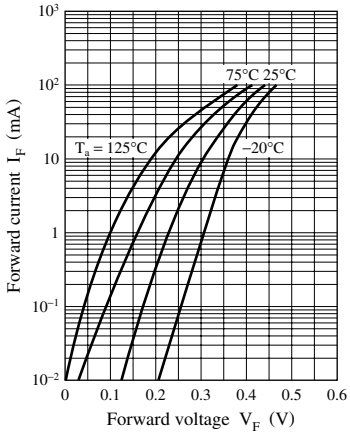
■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 100 mA			0.55	V
Reverse current	I_R	V_R = 30 V			15	µA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		20		pF
Reverse recovery time *	t_{rr}	I_F = I_R = 100 mA I_{rr} = 10 mA, R_L = 100 Ω		2.0		ns

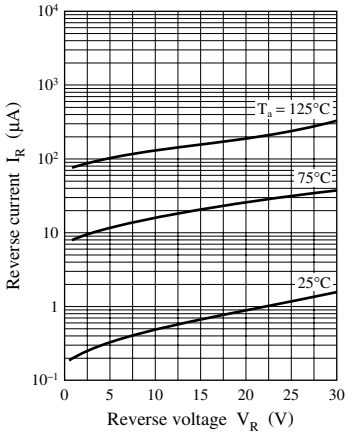
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. ∗: t_{rr} measurement circuit



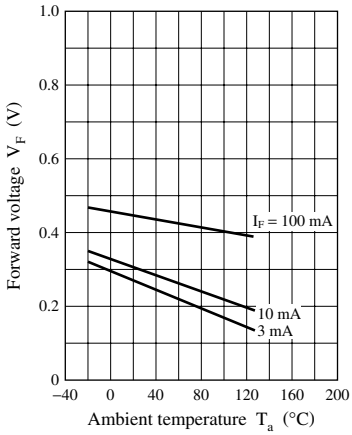
I_F — V_F



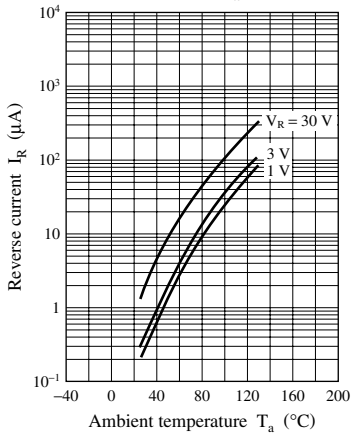
I_R — V_R



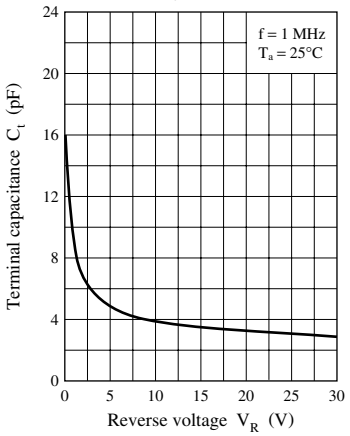
V_F — T_a



I_R — T_a

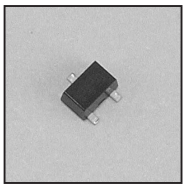


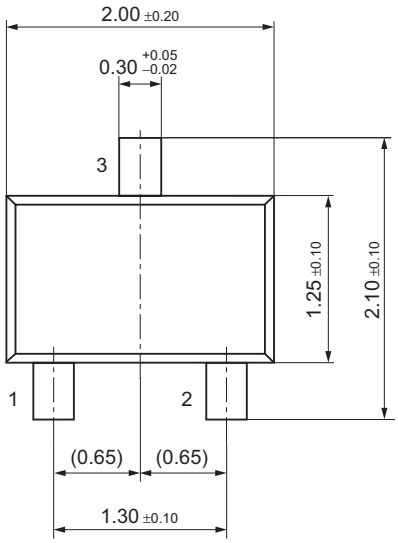
C_t — V_R

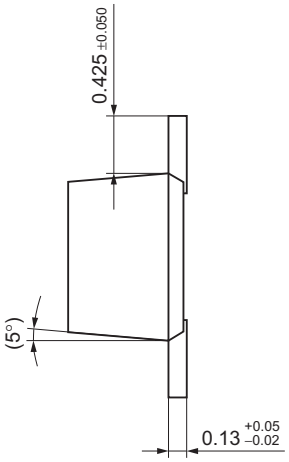


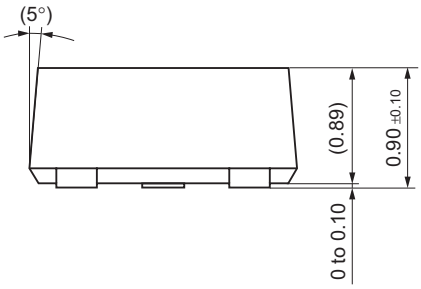
SMini3-F2

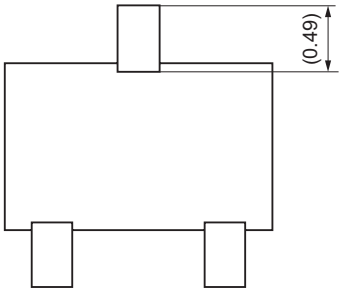
Unit: mm











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